

LTM4604 66LD 15mm X 9mm X 2.32mm (TABLE OF MATERIAL DECLARATION)

The LTM4604 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.212460	Barium Compounds	7727-43-7	0.0032	1.500
				Filler Substances (Silica Crystalline)	-	0.0848	39.915
				Copper Metal	7440-50-8	0.1190	56.000
				Copper Compounds	1328-53-6	0.0000	0.018
				Ecotoxic substances	7439-92-1	0.0000	0.000
				Gold metal or alloy	7440-57-5	0.0010	0.460
				Nickel	7440-02-0	0.0045	2.100
				Zinc	7440-66-6	0.0000	0.007
2	Solder Paste	Alloy	0.007900	Sn	7440-31-5	0.0075	95.000
				Sb	7440-36-0	0.0004	5.000
3	Passive/Active Components		0.2450	Ni Oxide	1313-99-1	0.0176	7.184
				Cu Oxide	1317-38-1	0.0059	2.416
				Zn Oxide	1314-13-2	0.0268	10.939
				Fe Oxide	1309-37-1	0.0977	39.863
				Copper (Cu)	7440-50-8	0.0390	15.919
				Nickel (Ni)	7440-02-0	0.00001	0.002
				Tin (Sn)	7440-31-5	0.0020	0.816
				Miscellaneous	-	0.0560	22.862
4	Active Ics	Silicon	0.003879	Silicon	7440-21-3	0.0039	100.000
5	Wire	Gold	0.000864	Au	7440-57-5	0.0009	100.000
6	Encapsulation	Epoxy Resin	0.526960	Fused Silica	60676-86-0	0.4068	77.200
				Epoxy Resin	-	0.0469	8.900
				Phenol Resin	-	0.0469	8.900
				Crytalline Silica	14808-60-7	0.0158	3.000
				Carbon Black	1333-86-4	0.0026	0.500
				Metal Hydroxide	-	0.0079	1.500
Total Package Weight			0.997053				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts